

**RoHS
Compliant**



3mm
MPR-14-0076

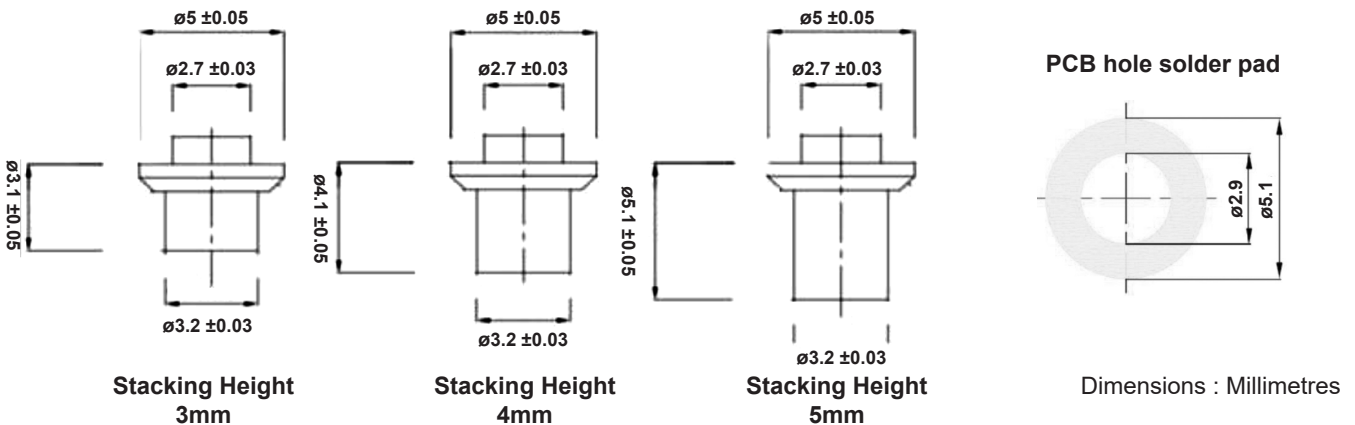
4mm
MPR-14-0075-F

5mm
MPR-14-0077

Specifications

Inner Raw Material : Ms58 (C3602) Copper alloy
 First Plating Layer : Copper Flash
 Second Plating Layer : Nickel plating (1µm)
 Third Plating Layer : Gold plating (0.8µm)
 Colour : Gold
 Stacking Heights : 3mm, 4mm and 5mm
 PCB Mating Board Thickness : 1.6mm
 Weight : 0.35g
 Operating Temperature : -40°C to +100°C

Diagram



Part Number Table

Description	Part Number
Pillar For Cinterion Module, 3mm	MPR-14-0076
Pillar For Cinterion Module, 4mm	MPR-14-0075-F
Pillar For Cinterion Module, 5mm	MPR-14-0077

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